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Dimensions

Chip Size	2824
L	7.1mm +/-0.4mm
W	6.1mm +/-0.4mm
T	2mm +/-0.20mm
B	1.27mm +/-0.4mm

Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	300

General Information

Series	SMD Indust COG HVHT200C Pulse
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Pulse Discharge, Ultra-Stable, Low Loss
Features	High Temperature
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	400 mg
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	0.033 uF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	10%
Voltage DC	630 VDC
Dielectric Withstanding Voltage	1250 VDC
Temperature Range	-55/+200°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	30.303 GOhms

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